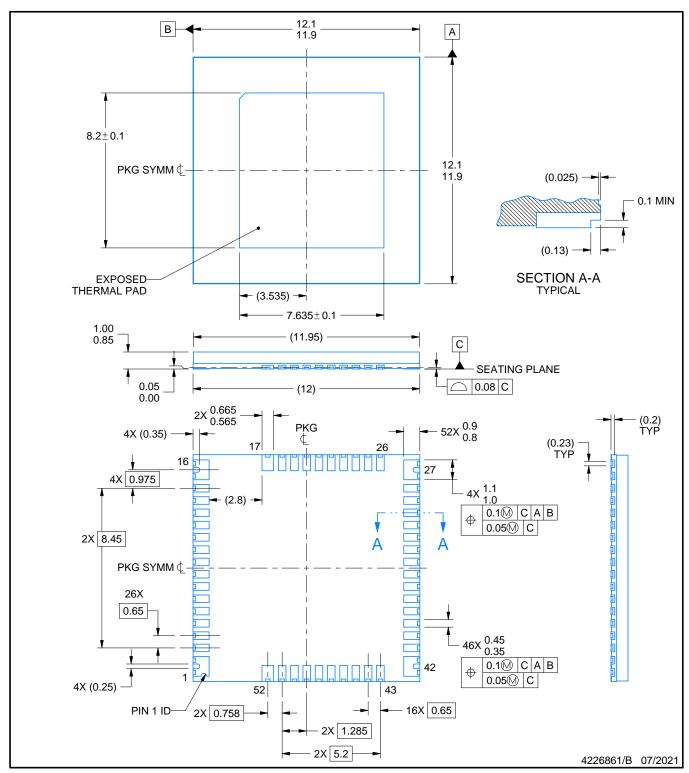


PLASTIC QUAD FLATPACK - NO LEAD



## NOTES:

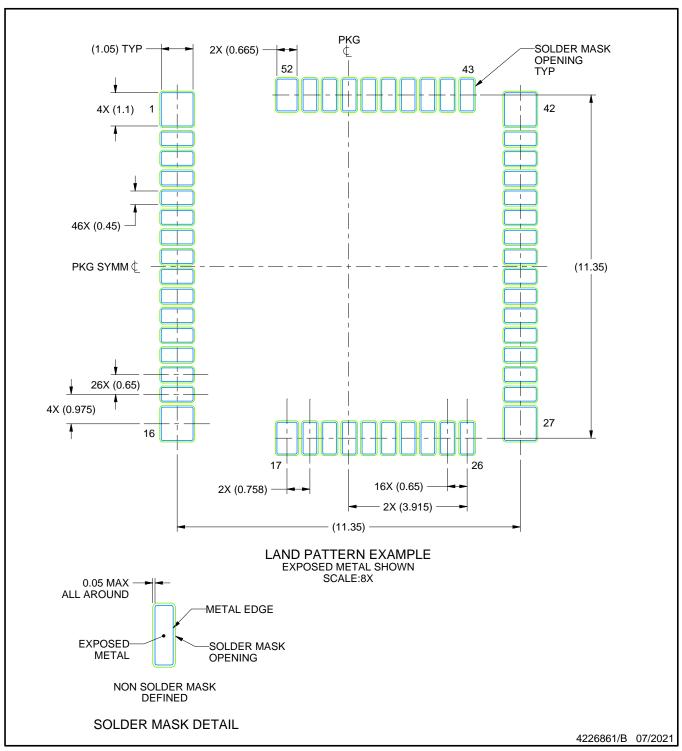
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This package incorporates an exposed thermal pad that is designed to be attached directly to an external heat sink. This optimizes the heat transfer from the integrated circuit (IC).



PLASTIC QUAD FLATPACK - NO LEAD

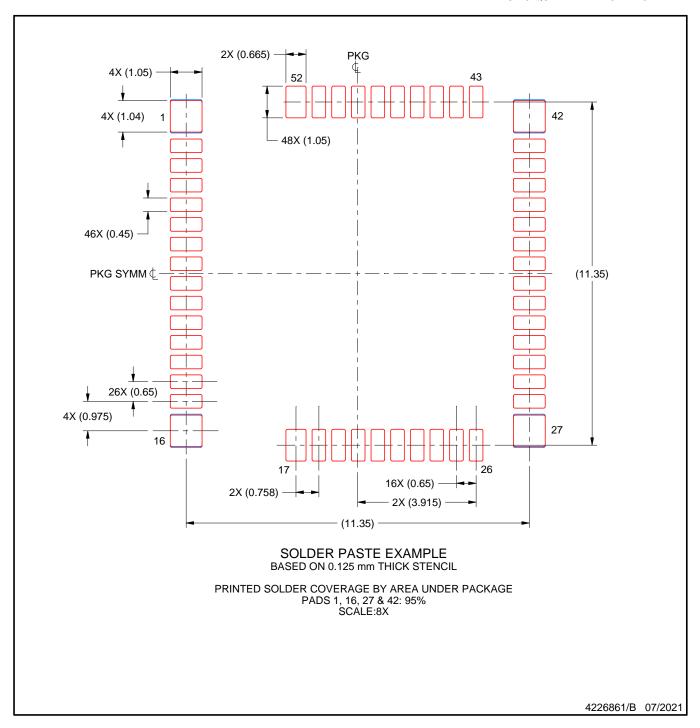


NOTES: (continued)

4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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